

23mm 低频玻璃封装应答机，只读，EN 14803 编号

查询样品: **TRPGR30ENATGA**

特性

- 由半双工 (HDX) 技术提供的同类产品最佳性能
- 获专利的应答机调谐提供稳定的和高读取性能
- **80 位只读类型**
- **EN 14803 编号**
- 对几乎所有非金属物质不敏感

应用范围

- 废弃集装箱管理

说明

德州仪器 (TI) 23mm 低频 (LF) 玻璃应答机提供出色性能并可在 134.2kHz 的共振频率上运行。此产品兼容 ISO/IEC 11784/11785 全球开放式标准。德州仪器 (TI) LF 玻璃应答机使用 TI 获专利的调谐制造工艺生产以提供持续的读取性能。送货前，将对此应答机进行全面的功能和参数测试，为用户提供他们希望从 TI 获得的高质量产品。



绝对最大额定值⁽¹⁾

在自然通风温度范围内运行（除非另有说明）

		TRPGR30ENATGA
T _A	工作温度	-25°C 至 70°C
T _{STG}	储存温度	-40°C 至 85°C

(1) 超出绝对最大额定值下列出的值的应力可能会对器件造成永久损坏。这些只是应力额定值，在这些额定值或者任何其它超过技术规格下所标明条件下的器件功能运行在此并未说明。长时间运行在绝对最大额定条件下会影响设备的可靠性。

技术规格

参数	TRPGR30ENATGA
功能	只读
存储器（位）	80（64 位唯一 ID + 16 位 BCC）
存储器（页）	1
共振频率	134.6kHz
调制	FSK（频移键控）134.2kHz 和 124.2kHz
发射原理	HDX（半双工）
电源	由读取器信号供电（无电池）
典型读取范围	≤ 110cm ⁽¹⁾
典型读取时间	70ms
外壳材料	玻璃
保护玻璃	密封
电磁兼容性 (EMC)	已编辑代码不受自然电磁干扰或 X 射线的影响。
信号渗透率	应答机能透过几乎全部非金属物质进行读取。
机械冲击	IEC 60068-2-32 自由落体测试，高度 1.5m，测试 20 次
尺寸	∅ 3.85 ± 0.05mm x 23.1 ± 0.5mm
重量	0.8g

(1) 取决于使用所在国家的 RF 管理规定，读取器天线配置和环境条件。



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TRPGR30ENATGA	Active	Production	RFIDT (TGA) 0	2000 LARGE T&R	Yes	Call TI	N/A for Pkg Type	-25 to 70	

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

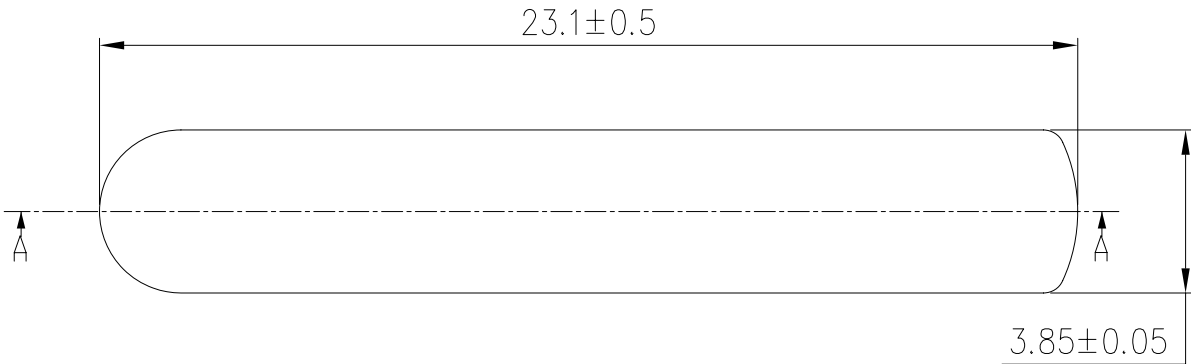
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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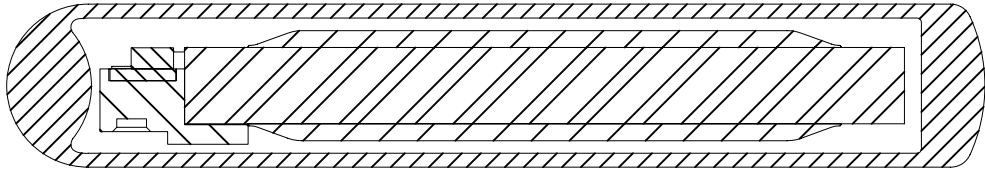
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TGA (R-RFID-N0)

RFIDT



A-A



4211903/A 06/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5-1994.
 - B. This drawing is subject to change without notice.
 - C. HDX+ 23mm Glass TRP Cap on Die.

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